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02/05/02

U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10062505	FILING DATE 02/05/2002	CLASS 438	SUBCLASS 7	GAU 2812	EXAMINER SE IER
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**APPLICANTS: Kawano Hiroyuki;

**CONTINUING DATA VERIFIED:

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** FOREIGN APPLICATIONS VERIFIED:
JAPAN 2001-065884 03/09/2001

PG-PUB ☐ DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no
35 USC 119 conditions met ☐ yes ☐ no

ATTORNEY DOCKET NO

OKI.304

Verified and Acknowledged Examiners's initials
TITLE : Method of manufacturing a semiconductor device including etching of a peripheral area before
chemical-mechanical polishing

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
ISSUE FEE			Total Claims	Print Claim for O.G.
Amount Due	Date Paid	Primary Examiner	DRAWING	
			Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner	
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